

30V N-Channel Enhancement Mode MOSFET

Voltage

30 V

Current

53 A

Features

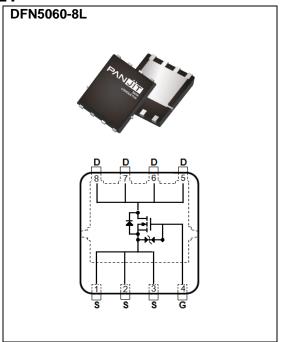
- RDS(ON), VGS@10V, ID@20A<7.5m Ω
- RDS(ON), VGS@4.5V, ID@10A<12.6m Ω
- Excellent FOM
- Logic Level Drive
- AEC-Q101 qualified
- Lead free in compliance with EU RoHS 2.0
- Green molding compound as per IEC 61249 standard

Mechanical Data

• Case: DFN5060-8L Package

• Terminals : Solderable per MIL-STD-750, Method 2026

• Approx. Weight: 0.08 grams



Maximum Ratings and Thermal Characteristics (T_A=25°C unless otherwise noted)

PARAMETER		SYMBOL	LIMIT	UNITS
Drain-Source Voltage		V _{DS}	30	V
Gate-Source Voltage		V _{GS}	±20	V
Continuous Drain Current(Note 3)	T _C =25°C		53	
	Tc=100°C	I _D	37	А
Pulsed Drain Current(Note 1)	T _C =25°C	I _{DM}	212	
Power Dissipation	T _C =25°C	_	33	,,,
	T _C =100°C	Po	17	W
Continuous Drain Current(Note 4)	T _A =25°C		16.7	
	T _A =70°C	I _D	14	Α
Power Dissipation	T _A =25°C	D	3.3	107
	T _A =70°C	Po	2.3	W
Single Pulse Avalanche Energy ^(Note 5)		Eas	25	mJ
Operating Junction and Storage Temperature Range		T _J ,T _{STG}	-55~175	°C
Thermal Resistance(Note 4)	Junction to Case	R _{0JC}	4.5	°C/W
	Junction to Ambient	R _{0JA}	45	C/VV



Electrical Characteristics (T_A=25°C unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS	
Static							
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250uA 30		-	-	V	
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250uA	1.3	1.8	2.5	V	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} =10V, I _D =20A	-	6	7.5	mΩ	
		V _{GS} =4.5V, I _D =10A	-	9.7	12.6		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V, V _{GS} =0V	-	-	±1	uA	
	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	-	-	±10	uA	
Gate-Source Leakage Current		V _{GS} =±10V, V _{DS} =0V	-	-	±1		
Dynamic ^(Note 6)							
Total Gate Charge	Q_g		-	12.4	-	nC	
Gate-Source Charge	Q _{gs}	V _{DS} =24V, I _D =20A,	-	2	-		
Gate-Drain Charge	Q_{gd}	V _{GS} =10V	-	3.4	-		
Input Capacitance	Ciss	\(\(\alpha\)	-	600	-		
Output Capacitance	Coss	V _{DS} =25V, V _{GS} =0V,	-	254	-	pF	
Reverse Transfer Capacitance	Crss	f=1MHz	-	71	-		
Gate resistance	Rg	f=1MHz	-	1.1	-	Ω	
Turn-On Delay Time	td _(on)	\\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	-	9	-	ns	
Turn-On Rise Time	tr	V _{DS} =24V, I _D =20A,	-	10	-		
Turn-Off Delay Time	td(off)	$V_{GS}=10V, R_{G}=3\Omega$	-	20	-		
Turn-Off Fall Time	tf	(14010-2)	-	16	-		
Drain-Source Diode	•						
Diode Forward Current	Is	Tc=25°C	-	-	53	А	
Pulsed Diode Forward Current	I _{SM}	1c=25 C	-	-	212		
Diode Forward Voltage	V _{SD}	Is=20A, V _{GS} =0V	-	0.79	1.1	V	
Reverse Recovery Time	Trr	V _{GS} =0V, I _S =20A	-	25	-	ns	
Reverse Recovery Charge	Qrr	dl _S /dt=100A/us	-	11	-	nC	

NOTES:

- 1. Pulse width<100us, Duty cycle<2%.
- 2. Essentially independent of operating temperature typical characteristics.
- 3. Chip capability with an R_{0JC}=4.5°C/W.
- 4. R_{BJA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. Mounted on a 1 inch² with 2oz.square pad of copper.
- 5. The test condition is L=0.5mH, I_{AS}=10A, V_{DD}=30V, V_{GS}=10V, Starting T_J=25°C. the chip is about to carry I_{AS}≈20A.
- 6. Guaranteed by design, not subject to production testing.

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TYPICAL CHARACTERISTIC CURVES

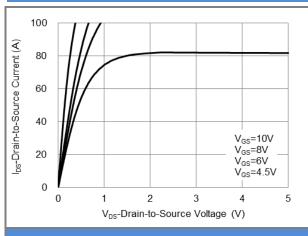


Fig.1 On-Region Characteristics

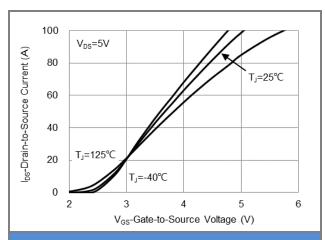


Fig.2 Transfer Characteristics

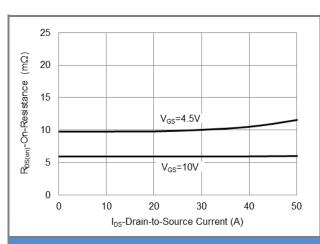


Fig.3 On-Resistance vs. Drain Current

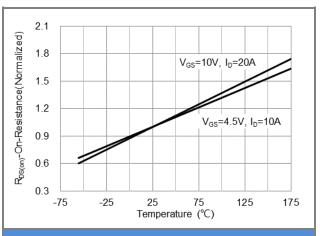
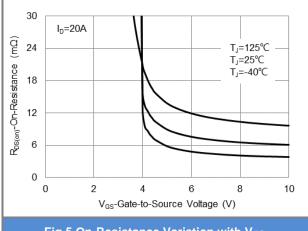
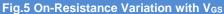


Fig.4 On-Resistance vs. Junction temperature





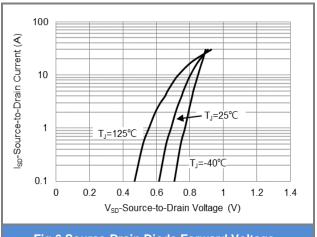


Fig.6 Source-Drain Diode Forward Voltage



TYPICAL CHARACTERISTIC CURVES

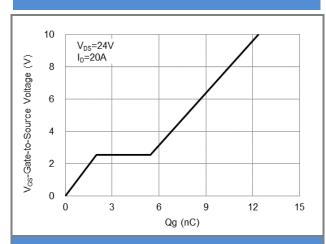


Fig.7 Gate-Charge Characteristics

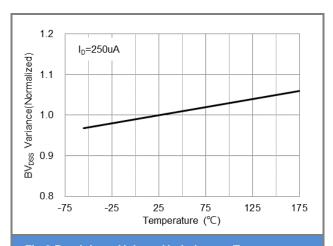


Fig.8 Breakdown Voltage Variation vs. Temperature

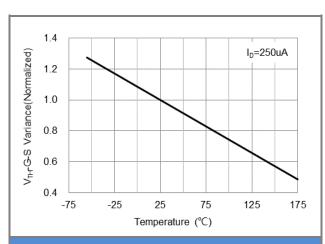


Fig.9 Threshold Voltage Variation with Temperature

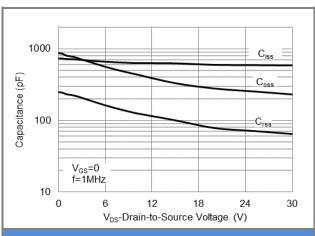


Fig.10 Capacitance vs. Drain-Source Voltage

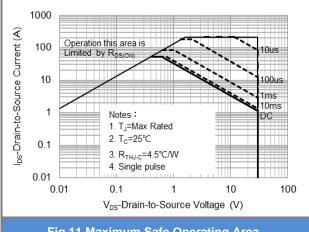
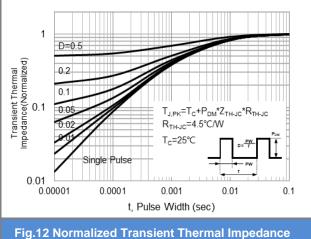


Fig.11 Maximum Safe Operating Area

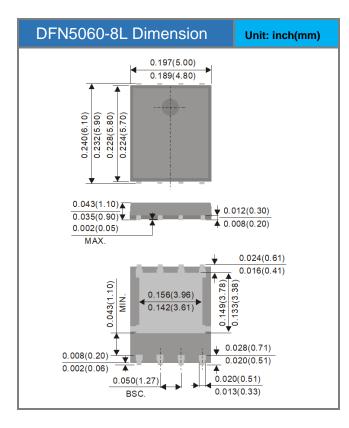


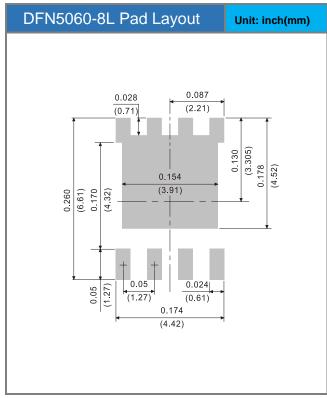


Product and Packing Information

Part No.	Package Type	Packing Type	Marking	
PJQ5530-AU	DFN5060-8L	3K pcs / 13" reel	Q5530	

Packaging Information & Mounting Pad Layout





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